INTEGRATED CIRCUITS

DATA SHEET

74HC1G125; **74HCT1G125**Bus buffer/line drivers; 3-state

Product specification Supersedes data of 2002 May 17 2004 Jul 27





Bus buffer/line drivers; 3-state

74HC1G125; 74HCT1G125

FEATURES

- Wide supply voltage range from 2.0 to 6.0 V
- · Symmetrical output impedance
- · High noise immunity
- · Low power dissipation
- · Balanced propagation delays
- Very small 5 pins package
- · Output capability: bus driver.

DESCRIPTION

The 74HC1G/HCT1G125 is a high-speed Si-gate CMOS device.

The 74HC1G/HCT1G125 provides one non-inverting buffer/line driver with 3-state output. The 3-state output is controlled by the output enable input pin (\overline{OE}) . A HIGH at pin \overline{OE} causes the output as assume a high-impedance OFF-state.

The bus driver output currents are equal compared to the 74HC/HCT125.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25 \, ^{\circ}C$; $t_r = t_f \le 6.0 \, \text{ns}$.

CAMBOI	PARAMETER	CONDITIONS	TYP	UNIT	
SYMBOL	PARAMETER	CONDITIONS	HC1G	HCT1G	UNII
t _{PHL} /t _{PLH}	propagation delay A to Y	C _L = 15 pF; V _{CC} = 5 V	9	10	ns
C _I	input capacitance		1.5	1.5	pF
C _{PD}	power dissipation capacitance	notes 1 and 2	30	27	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$$
 where:

 f_i = input frequency in MHz;

fo = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts;

 $\sum (C_L \times V_{CC}^2 \times f_0) = \text{sum of outputs.}$

2. For HC1G the condition is $V_I = GND$ to V_{CC} .

For HCT1G the condition is $V_I = GND$ to $V_{CC} - 1.5 V$.

FUNCTION TABLE

See note 1.

INP	OUTPUT	
ŌĒ	Α	Y
L	L	L
L	Н	Н
Н	X	Z

Note

- 1. H = HIGH voltage level;
 - L = LOW voltage level;
 - X = don't care;
 - Z = high-impedance OFF-state.

Bus buffer/line drivers; 3-state

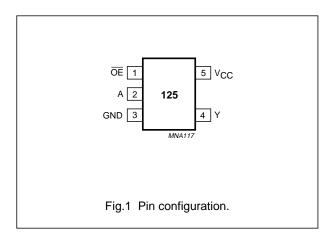
74HC1G125; 74HCT1G125

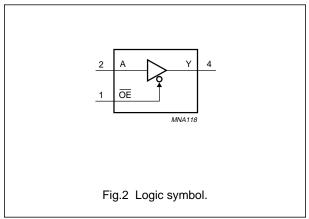
ORDERING INFORMATION

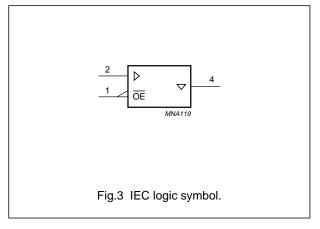
	PACKAGE								
TYPE NUMBER	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE	MARKING			
74HC1G125GW	-40 to +125 °C	5	SC-88A	plastic	SOT353	HM			
74HCT1G125GW	–40 to +125 °C	5	SC-88A	plastic	SOT353	TM			
74HC1G125GV	-40 to +125 °C	5	SC-74A	plastic	SOT753	H25			
74HCT1G125GV	-40 to +125 °C	5	SC-74A	plastic	SOT753	T25			

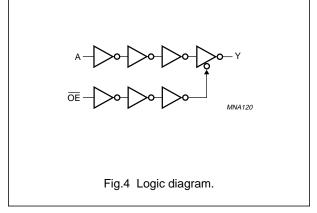
PINNING

PIN	SYMBOL	DESCRIPTION
1	ŌĒ	output enable input
2	A	data input A
3	GND	ground (0 V)
4	Υ	data output Y
5	V _{CC}	supply voltage









Bus buffer/line drivers; 3-state

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	74HC1G125			74HCT1G125			UNIT
STIVIBUL	PARAMETER		MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	UNII
V _{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
VI	input voltage		0	_	V _{CC}	0	_	V _{CC}	V
Vo	output voltage		0	_	V _{CC}	0	_	V _{CC}	V
T _{amb}	operating ambient temperature	see DC and AC characteristics per device	-40	+25	+125	-40	+25	+125	°C
t _r , t _f	input rise and fall times	V _{CC} = 2.0 V	_	_	1000	_	_	_	ns
		V _{CC} = 4.5 V	_	_	500	_	_	500	ns
		V _{CC} = 6.0 V	_	_	400	_	_	_	ns

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	PARAMETER CONDITIONS			
V _{CC}	supply voltage		-0.5	+7.0	V
I _{IK}	input diode current	$V_I < -0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}; \text{ note 1}$	_	±20	mA
I _{OK}	output diode current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}; \text{ note 1}$	_	±20	mA
Io	output source or sink current	-0.5 V < V _O < V _{CC} + 0.5 V; note 1	_	±12.5	mA
I _{CC}	V _{CC} or GND current	note 1	_	±25	mA
T _{stg}	storage temperature		-65	+150	°C
P _D	power dissipation per package	for temperature range from -40 to +125 °C; note 2	_	200	mW

Notes

- 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- 2. Above 55 $^{\circ}\text{C}$ the value of P_D derates linearly with 2.5 mW/K.

Bus buffer/line drivers; 3-state

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DC CHARACTERISTICS

Family 74HC1G

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

		TEST CONDIT	IONS	T _{amb} (°C)					
SYMBOL	PARAMETER			−40 to +85			-40 to +125		UNIT
		OTHER V	V _{CC} (V)	MIN.	TYP. (1)	MAX.	MIN.	MAX.	
V _{IH}	HIGH-level input voltage		2.0	1.5	1.2	_	1.5	_	V
			4.5	3.15	2.4	_	3.15	_	V
			6.0	4.2	3.2	_	4.2	_	V
V _{IL}	LOW-level input voltage		2.0	_	0.8	0.5	_	0.5	V
			4.5	_	2.1	1.35	_	1.35	V
			6.0	_	2.8	1.8	_	1.8	V
V _{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = -20 \mu A$	2.0	1.9	2.0	_	1.9	-	V
		$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = -20 \mu A$	4.5	4.4	4.5	_	4.4	_	V
		$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = -20 \mu A$	6.0	5.9	6.0	-	5.9	_	V
		$V_I = V_{IH}$ or V_{IL} ; $I_O = -2.0$ mA	4.5	4.13	4.32	-	3.7	_	V
		$V_I = V_{IH}$ or V_{IL} ; $I_O = -2.6$ mA	6.0	5.63	5.81	-	5.2	-	V
V _{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = 20 \mu\text{A}$	2.0	_	0	0.1	-	0.1	V
		$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = 20 \mu\text{A}$	4.5	_	0	0.1	-	0.1	V
		$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = 20 \mu\text{A}$	6.0	_	0	0.1	_	0.1	V
		$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = 2.0 \text{ mA}$	4.5	_	0.15	0.33	_	0.4	V
		$V_I = V_{IH}$ or V_{IL} ; $I_O = 2.6$ mA	6.0	_	0.16	0.33	_	0.4	V
I _{LI}	input leakage current	$V_I = V_{CC}$ or GND	6.0	_	_	1.0	_	1.0	μΑ
I _{OZ}	3-state output current OFF-state	$V_I = V_{IH} \text{ or } V_{IL};$ $V_O = V_{CC} \text{ or GND}$	6.0	_	-	5	-	10	μА
I _{CC}	quiescent supply current	$V_I = V_{CC}$ or GND; $I_O = 0$	6.0	_	-	10	-	20	μА

Note

1. All typical values are measured at T_{amb} = 25 $^{\circ}C.$

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Family 74HCT1G

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

		TEST CONDITIONS		T _{amb} (°C)					
SYMBOL	PARAMETER	OTHER	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	−40 to +85			-40 to +125		UNIT
		OTHER V _C	V _{CC} (V)	MIN.	TYP. (1)	MAX.	MIN.	MAX.	1
V _{IH}	HIGH-level input voltage		4.5 to 5.5	2.0	1.6	-	2.0	_	V
V _{IL}	LOW-level input voltage		4.5 to 5.5	_	1.2	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = -20 \mu\text{A}$	4.5	4.4	4.5	-	4.4	_	V
		$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = -2.0 \text{ mA}$	4.5	4.13	4.32	-	3.7	_	V
V _{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = 20 \mu A$	4.5	_	0	0.1	-	0.1	V
		$V_I = V_{IH} \text{ or } V_{IL};$ $I_O = 2.0 \text{ mA}$	4.5	_	0.15	0.33	-	0.4	V
I _{LI}	input leakage current	$V_I = V_{CC}$ or GND	5.5	_	-	1.0	-	1.0	μΑ
I _{OZ}	3-state output current OFF-state	$V_I = V_{IH} \text{ or } V_{IL};$ $V_O = V_{CC} \text{ or GND}$	5.5	_	_	5	-	10	μΑ
I _{CC}	quiescent supply current	$V_I = V_{CC}$ or GND; $I_O = 0$	5.5	-	_	10	-	20	μΑ
ΔI_{CC}	additional supply current per input	$V_{I} = V_{CC} - 2.1 \text{ V};$ $I_{O} = 0$	4.5 to 5.5	_	-	500	-	850	μΑ

Note

^{1.} All typical values are measured at T_{amb} = 25 °C.

Bus buffer/line drivers; 3-state

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AC CHARACTERISTICS

Type 74HC1G125

GND = 0 V; $t_r = t_f \le 6.0$ ns; $C_L = 50$ pF.

		TEST CONDITI	TEST CONDITIONS		T _{amb} (°C)				
SYMBOL	PARAMETER	WAVEFORMS	V 00	-	-40 to +8	5	-40 to +125		UNIT
			V _{CC} (V)	MIN.	TYP. ⁽¹⁾	MAX.	MIN.	MAX.	
t _{PHL} /t _{PLH}	propagation delay	see Figs 5 and 7	2.0	_	24	125	_	150	ns
A to Y		4.5	_	10	25	_	30	ns	
			6.0	_	8	21	_	26	ns
t _{PZH} /t _{PZL}	3-state output	see Figs 6 and 7	2.0	_	19	155	_	190	ns
	enable time		4.5	_	9	31	_	38	ns
	OE to Y		6.0	_	7	26	_	32	ns
t _{PHZ} /t _{PLZ}	3-state output	see Figs 6 and 7	2.0	_	18	155	_	190	ns
	disable time		4.5	_	12	31	_	38	ns
	OE to Y		6.0	_	11	26	_	32	ns

Note

1. All typical values are measured at T_{amb} = 25 °C.

Type 74HCT1G125

GND = 0 V; $t_r = t_f \le 6.0$ ns; $C_L = 50$ pF.

		TEST CONDITIONS							
SYMBOL	PARAMETER	MANGEODMO	V 00	−40 to +85			-40 to +125		UNIT
		WAVEFORMS	V _{CC} (V)	MIN.	TYP. ⁽¹⁾	MAX.	MIN.	MAX.	
t _{PHL} /t _{PLH}	propagation delay A to Y	see Figs 5 and 7	4.5	-	11	30	_	36	ns
t _{PZH} /t _{PZL}	3-state output enable time OE to Y	see Figs 6 and 7	4.5	_	10	35	-	42	ns
t _{PHZ} /t _{PLZ}	3-state output disable time OE to Y	see Figs 6 and 7	4.5	_	11	31	_	38	ns

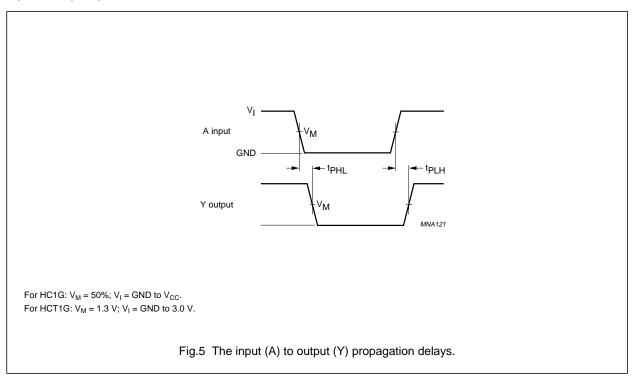
Note

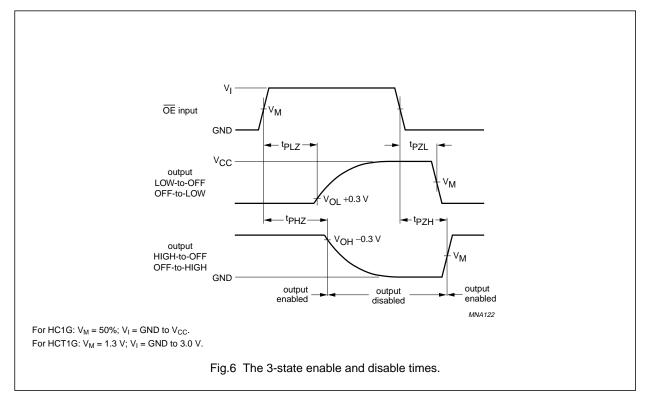
1. All typical values are measured at T_{amb} = 25 °C.

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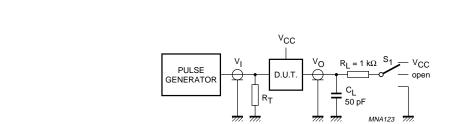
AC WAVEFORMS





Bus buffer/line drivers; 3-state

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TEST	S ₁
t _{PLH} /t _{PHL}	open
t _{PLZ} /t _{PZL}	V _{CC}
t _{PHZ} /t _{PZH}	GND

Definitions for test circuit:

 C_L = load capacitance including jig and probe capacitance (see "AC characteristics").

 R_T = termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig.7 Load circuitry for switching times.

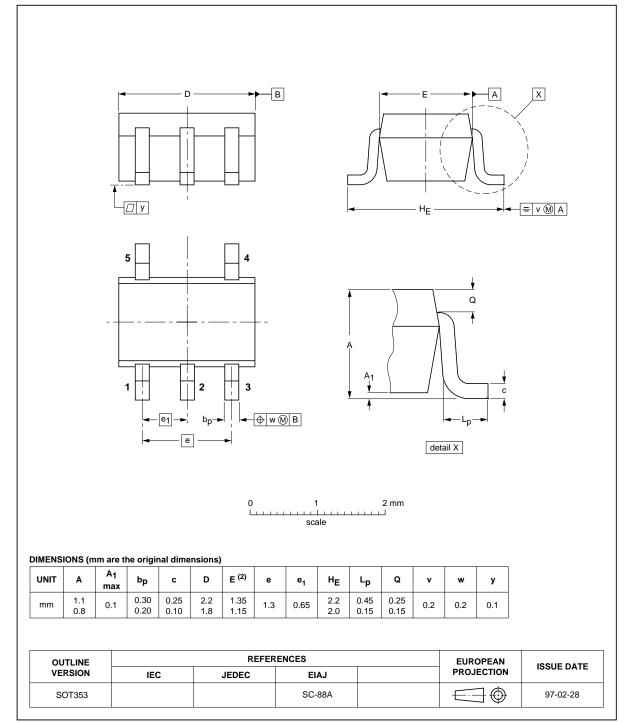
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PACKAGE OUTLINES

Plastic surface mounted package; 5 leads

SOT353



Bus buffer/line drivers; 3-state

74HC1G125; 74HCT1G125

SOT753 Plastic surface mounted package; 5 leads В A = v M A detail X **DIMENSIONS** (mm are the original dimensions) $^{\rm H_{\rm E}}$ Ε Q Α1 е bp Lp у 0.100 0.26 3.1 1.7 3.0 0.6 0.33 1.1 mm 0.95 0.2 0.1 0.9 0.013 0.10 2.7 1.3 2.5 REFERENCES EUROPEAN PROJECTION OUTLINE ISSUE DATE **VERSION** IEC **JEDEC JEITA** $\bigoplus \bigoplus$ SOT753 SC-74A 02-04-16

Bus buffer/line drivers; 3-state

74HC1G125; 74HCT1G125

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
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